# **General Purpose Transistor**

## **NPN Silicon**

### **Features**

- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant\*

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V <sub>CEO</sub>	45	Vdc
Collector - Base Voltage	$V_{CBO}$	50	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	5.0	Vdc
Collector Current - Continuous	I <sub>C</sub>	100	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1.  $FR-5 = 1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.

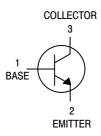


## ON Semiconductor®

http://onsemi.com



SOT-23 (TO-236) CASE 318-08 STYLE 6



## **MARKING DIAGRAM**



K2 = Device CodeM = Date Code\*■ = Pb-Free Package

= PD-Free Package

vary depending upon manufacturing location.

(Note: Microdot may be in either location)\*Date Code orientation and/or overbar may

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
BCW72LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SBCW72LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

1

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage ( $I_C = 2.0 \text{ mAdc}, V_{EB} = 0$ )	V <sub>(BR)CEO</sub>	45	-	_	Vdc
Collector - Emitter Breakdown Voltage (I <sub>C</sub> = 2.0 mAdc, V <sub>EB</sub> = 0)	V <sub>(BR)CES</sub>	45	-	_	Vdc
Collector – Base Breakdown Voltage $(I_C = 10 \mu Adc, I_E = 0)$	V <sub>(BR)</sub> CBO	50	-	_	Vdc
Emitter – Base Breakdown Voltage ( $I_E = 10 \mu Adc, I_C = 0$ )	V <sub>(BR)EBO</sub>	5.0	-	_	Vdc
Collector Cutoff Current $(V_{CB} = 20 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 20 \text{ Vdc}, I_E = 0, T_A = 100^{\circ}\text{C})$	Ісво	- -	- -	100 10	nAdc μAdc
ON CHARACTERISTICS					
DC Current Gain (I <sub>C</sub> = 2.0 mAdc, V <sub>CE</sub> = 5.0 Vdc)	h <sub>FE</sub>	200	-	450	-
Collector – Emitter Saturation Voltage ( $I_C = 10 \text{ mAdc}$ , $I_B = 0.5 \text{ mAdc}$ ) ( $I_C = 50 \text{ mAdc}$ , $I_B = 2.5 \text{ mAdc}$ )	V <sub>CE(sat)</sub>	- -	- 0.21	0.25 –	Vdc
Base – Emitter Saturation Voltage ( $I_C = 50 \text{ mAdc}$ , $I_B = 2.5 \text{ mAdc}$ )	V <sub>BE(sat)</sub>	-	0.85	-	Vdc
Base – Emitter On Voltage (I <sub>C</sub> = 2.0 mAdc, V <sub>CE</sub> = 5.0 Vdc)	V <sub>BE(on)</sub>	0.6	-	0.75	Vdc
SMALL-SIGNAL CHARACTERISTICS			•	•	•
Current – Gain – Bandwidth Product (I <sub>C</sub> = 10 mAdc, V <sub>CE</sub> = 5.0 Vdc, f = 100 MHz)	f <sub>T</sub>	-	300	_	MHz
Output Capacitance (I <sub>E</sub> = 0, V <sub>CB</sub> = 10 Vdc, f = 1.0 MHz)	C <sub>obo</sub>	_	-	4.0	pF
Input Capacitance (I <sub>E</sub> = 0, V <sub>CB</sub> = 10 Vdc, f = 1.0 MHz)	C <sub>ibo</sub>	-	9.0	-	pF
Noise Figure (I <sub>C</sub> = 0.2 mAdc, V <sub>CE</sub> = 5.0 Vdc, R <sub>S</sub> = 2.0 k $\Omega$ , f = 1.0 kHz, BW = 200	0 Hz)	-	-	10	dB

## **EQUIVALENT SWITCHING TIME TEST CIRCUITS**

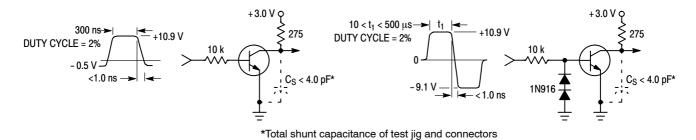


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

#### TYPICAL NOISE CHARACTERISTICS

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}C)$ 

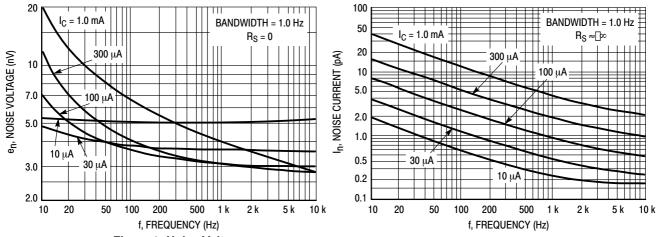


Figure 3. Noise Voltage

Figure 4. Noise Current

## **NOISE FIGURE CONTOURS**

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}C)$ 

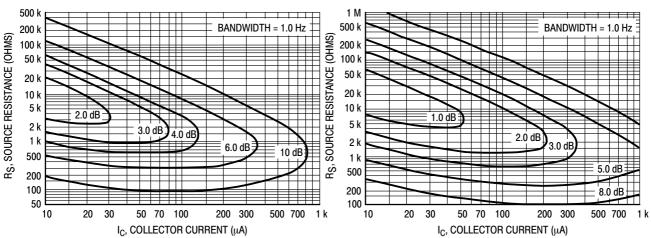


Figure 5. Narrow Band, 100 Hz

Figure 6. Narrow Band, 1.0 kHz

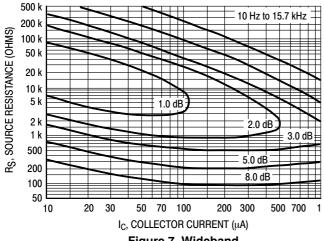


Figure 7. Wideband

Noise Figure is defined as:

$$NF = 20 \log_{10} \left( \frac{e_n^2 + 4KTR_S + I_n^2 R_S^2}{4KTR_S} \right)^{1/2}$$

en = Noise Voltage of the Transistor referred to the input. (Figure 3)

 $I_n$  = Noise Current of the Transistor referred to the input. (Figure 4)

K = Boltzman's Constant (1.38 x  $10^{-23}$  j/°K)

T = Temperature of the Source Resistance (°K)

R<sub>S</sub> = Source Resistance (Ohms)

#### TYPICAL STATIC CHARACTERISTICS

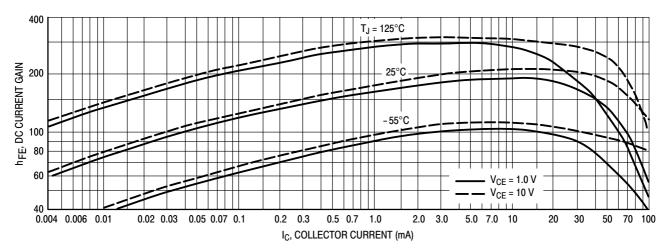


Figure 8. DC Current Gain

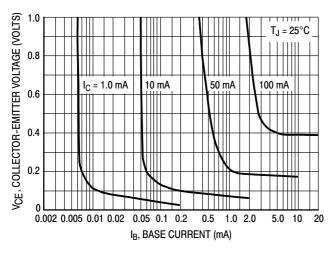


Figure 9. Collector Saturation Region

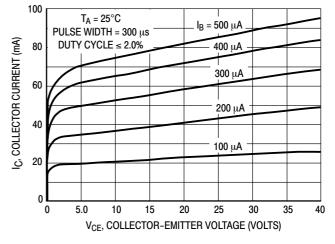


Figure 10. Collector Characteristics

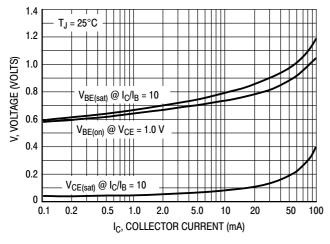


Figure 11. "On" Voltages

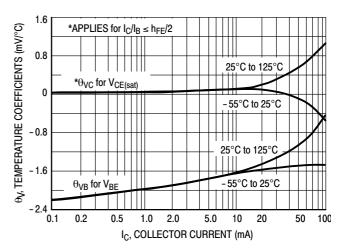
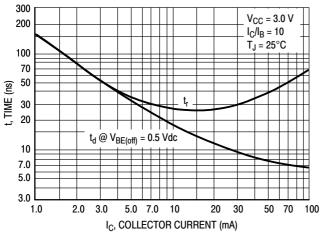


Figure 12. Temperature Coefficients

#### TYPICAL DYNAMIC CHARACTERISTICS



I<sub>C</sub>, COLLECTOR CURRENT (mA)

Figure 13. Turn-On Time

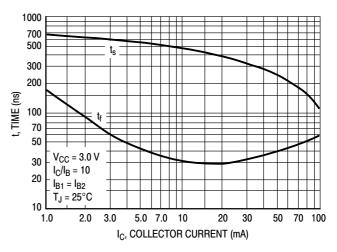


Figure 14. Turn-Off Time

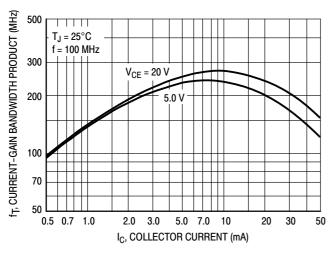


Figure 15. Current-Gain — Bandwidth Product

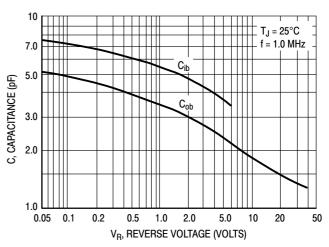


Figure 16. Capacitance

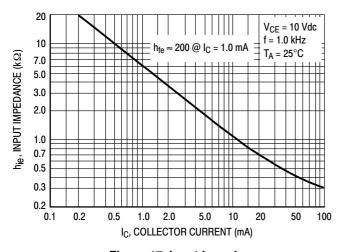


Figure 17. Input Impedance

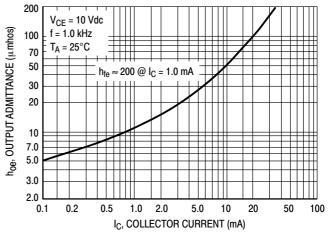


Figure 18. Output Admittance

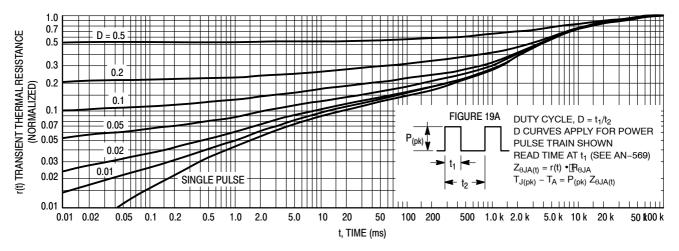


Figure 19. Thermal Response

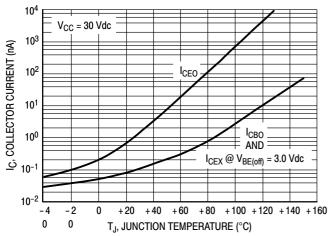


Figure 19A.

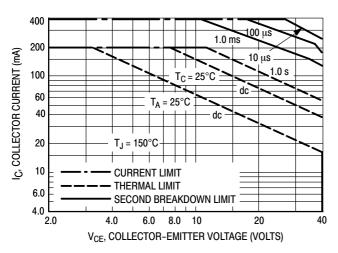


Figure 20.

### **DESIGN NOTE: USE OF THERMAL RESPONSE DATA**

A train of periodical power pulses can be represented by the model as shown in Figure 19A. Using the model and the device thermal response the normalized effective transient thermal resistance of Figure 19 was calculated for various duty cycles.

To find  $Z_{\theta,JA(t)}$ , multiply the value obtained from Figure 19 by the steady state value  $R_{\theta,JA}$ .

Example:

The MPS3904 is dissipating 2.0 watts peak under the following conditions:

 $t_1 = 1.0 \text{ ms}, t_2 = 5.0 \text{ ms}. (D = 0.2)$ 

Using Figure 19 at a pulse width of 1.0 ms and D=0.2, the reading of r(t) is 0.22.

The peak rise in junction temperature is therefore

 $\Delta T = r(t) \times P_{(pk)} \times R_{\theta JA} = 0.22 \times 2.0 \times 200 = 88^{\circ}C.$ 

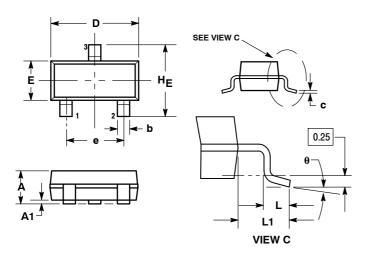
For more information, see AN-569.

The safe operating area curves indicate  $I_C-V_{CE}$  limits of the transistor that must be observed for reliable operation. Collector load lines for specific circuits must fall below the limits indicated by the applicable curve.

The data of Figure 20 is based upon  $T_{J(pk)}=150^{\circ}C$ ;  $T_{C}$  or  $T_{A}$  is variable depending upon conditions. Pulse curves are valid for duty cycles to 10% provided  $T_{J(pk)} \le 150^{\circ}C$ .  $T_{J(pk)}$  may be calculated from the data in Figure 19. At high case or ambient temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

#### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AP** 



- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
  MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
  THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

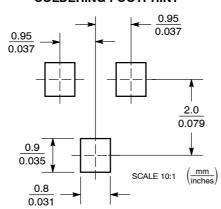
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°

### STYLE 6:

PIN 1. BASE

- 2 **EMITTER**
- COLLECTOR 3.

#### **SOLDERING FOOTPRINT**



ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice on semiconductor and are registered readerlands of semiconductor Components industries, Ite (SCILLC) . Solitude services are inject to make triangles without further holice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor:

BCW72LT1G SBCW72LT1G